

Appln No. 09/650,275
Amdt date August 31, 2004
Reply to Office action of July 8, 2004

Amendments to the Specification:

Please amend the paragraph on page 5, starting at line 19, to read as follows:

Seal ring 300 extends around the periphery of semiconductor die 310 and encompasses the digital circuit area 314 and the analog circuit area 316. The seal ring 300 of the preferred embodiment has the same structure as prior art seal ring 200 shown in Figure 1. Seal ring 300 physically connects the substrate along the entire length of elongate region 302. Seal ring 300 also physically contacts the substrate at the gap 304 between the ends 322, 323 of elongate region 302. Substrate 308 makes electrical contact with seal ring 300 ~~302~~ solely at the gap 304 where the substrate physically contacts the seal ring without the intervening well region 302 of opposite conductivity type (or other insulator). A single partially conducting path illustrate by resistor 325 extends through substrate 308 to the section of seal ring 302 in electrical contact with the substrate at gap 304.